#### **SPECIFICATION**

CUSTOMER :	
<b>MODULE NO.:</b>	LC2004L-TFH-ET

APPROVED BY:		
(FOR CUSTOMER USE ONLY)	PCB VERSION:	DATA:

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY

VERSION	DATE	REVISED PAGE NO.	SUMMARY

## **1.Contents**

- 1. Module Classification Information
- 2.Precautions in use of LCD Modules
- **3.**General Specification
- 4. Absolute Maximum Ratings
- **5.**Electrical Characteristics
- **6.Optical Characteristics**
- 7.Interface Pin Function
- 8. Contour Drawing & Block Diagram
- 9. Character Generator ROM Pattern
- 10.Reliability
- 11.Backlight Information
- 12.Inspection specification
- 13. Material List of Components for RoHs
- 14. Recommendable Storage

## **2.Precautions in use of LCD Modules**

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6)Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8) Producer has the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9)Producer has the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions. Producer has the right to modify the version.)
- (10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.

## **3.General Specification**

Item	Dimension	Unit
Number of Characters	20 characters x 4Lines	_
Module dimension	146.0 x 62.5 x 13.6	mm
View area	123.5 x 43.0	mm
Active area	118.84 x 38.47	mm
Dot size	0.92 x 1.10	mm
Dot pitch	0.98 x 1.16	mm
Character size	4.84 x 9.22	mm
Character pitch	6.0 x 9.75	mm
LCD type	FSTN, Positive, Transflective Mode (In LCD production, It will occur slightly color dif only guarantee the same color in the same batc	
Duty	1/16	
View direction	6 o'clock	
Backlight Type	LED, white	
IC	ST7066U or equivalent	

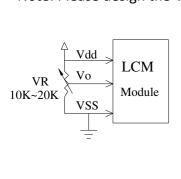
## **4.Absolute Maximum Ratings**

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	Тор	-20	_	+70	°C
Storage Temperature	T <sub>ST</sub>	-30	_	+80	°C
Input Voltage	VI	V <sub>SS</sub>	_	V <sub>DD</sub>	V
Supply Voltage For Logic	VDD-V <sub>SS</sub>	-0.3		7	V
Supply Voltage For LCD	V <sub>DD</sub> -V <sub>o</sub>	-0.3		13	V

### **5.Electrical Characteristics**

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	V <sub>DD</sub> -V <sub>SS</sub>	_	4.5	5.0	5.5	V
Supply Voltage For LCD		Ta=-20°C	_		5.4	V
*Note	$V_{DD}$ - $V_0$	Ta=25℃	4.1	4.2	4.3	V
		Ta=70°C	3.5	—	_	V
Input High Volt.	V <sub>IH</sub>	_	$0.7 V_{DD}$		V <sub>DD</sub>	V
Input Low Volt.	V <sub>IL</sub>	_	V <sub>SS</sub>		0.6	V
Output High Volt.	V <sub>OH</sub>		3.9		VDD	V
Output Low Volt.	V <sub>OL</sub>		0	_	0.4	V
Supply Current	I <sub>DD</sub>	V <sub>DD</sub> =5.0V	1.0	2.0	4.0	mA

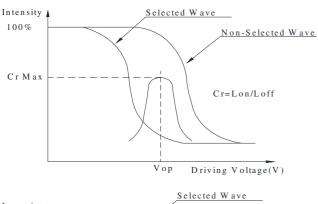
\* Note: Please design the VOP adjustment circuit on customer's main board

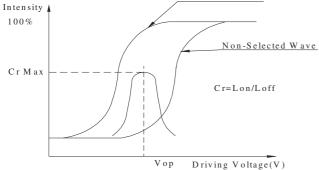


## **6.Optical Characteristics**

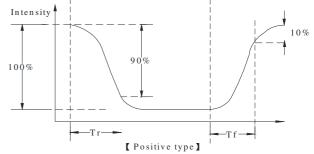
Item	Symbol	Condition	Min	Тур	Max	Unit
	$\theta$	$CR \ge 2$	0		30	$\phi = 180^{\circ}$
View Angle	$\theta$	$CR \ge 2$	0	_	60	$\phi = 0^{\circ}$
	θ	$CR \ge 2$	0		45	$\phi = 90^{\circ}$
	heta	$CR \ge 2$	0		45	$\phi = 270^{\circ}$
Contrast Ratio	CR			5		_
	T rise			150	200	ms
Response Time	T fall	—	_	150	200	ms

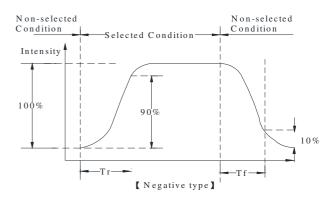
Definition of Operation Voltage (Vop)







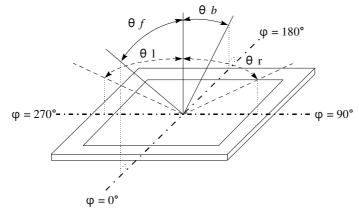




#### **Conditions :**

Operating Voltage : Vop Frame Frequency : 64 HZ Viewing Angle( $\theta$ ,  $\phi$ ): 0°, 0° Driving Waveform: 1/N duty, 1/a bias

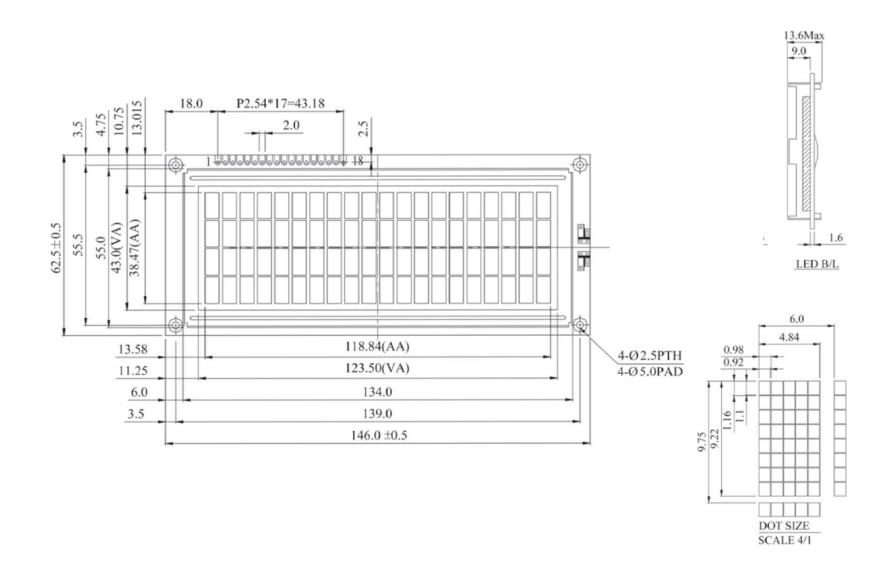
#### Definition of viewing angle(CR $\geq$ 2)

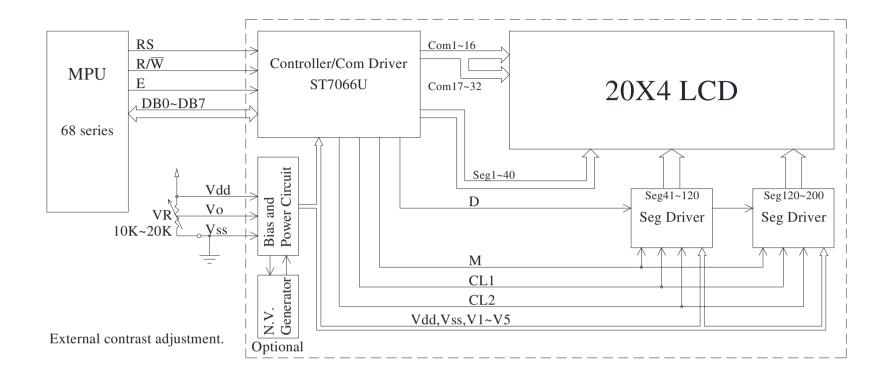


## **7.Interface Pin Function**

Pin No.	Symbol	Level	Description
1	V <sub>SS</sub>	0V	Ground
2	$V_{DD}$	5.0V	Supply Voltage for logic
3	VO	(Variable)	Operating voltage for LCD
4	RS	H/L	H: DATA, L: Instruction code
5	R/W	H/L	H: Read L: Write
6	Е	H,H→L	Chip enable signal
7	DB0	H/L	Data bus line
8	DB1	H/L	Data bus line
9	DB2	H/L	Data bus line
10	DB3	H/L	Data bus line
11	DB4	H/L	Data bus line
12	DB5	H/L	Data bus line
13	DB6	H/L	Data bus line
14	DB7	H/L	Data bus line
15	А		Power supply for B/L(+)
16	K		Power supply for B/L(-)
17	NC		No connection
18	NC		No connection

#### **8.Contour Drawing & Block Diagram**





Character located	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20
DDRAM address	00	01	02	03	04	05	06	07	08	09	0A	0B	0C	0D	0E	0F	10	11	12	13
DDRAM address	40	41	42	43	44	45	46	47	48	49	4A	4 <b>B</b>	4C	4D	4E	4F	50	51	52	53
DDRAM address	14	15	16	17	18	19	1A	1 <b>B</b>	1 <b>C</b>	1D	1E	1F	20	21	22	23	24	25	26	27
DDRAM address	54	55	56	57	58	59	5A	5B	5C	5D	5E	5F	60	61	62	63	64	65	66	67

#### **9.Character Generator ROM Pattern**

Table.2

b7-b4	0000	0001	0010	0011	0100	0101	0110	0111	1000	1001	1010	1011	1100	1101	1110	1111
<u>ьз-ьо</u> 0000	CG RAM (1)															
0001	(2)															
0010	(3)															
0011	(4)															
0100	(5)															
0101	(6)															
0110	0															
0111	(8)															
1000	θ															
1001	(2)															
1010	3															
1011	(4)															
1100	(5)															
1101	(6)															
1110	(7)															
1111	(8)															

## **10.Reliability**

Content of Reliability Test (Wide temperature, -20 $^{\circ}$ C ~70 $^{\circ}$ C)

	<b>Environmental Test</b>		
Test Item	Content of Test	Test Condition	Not e
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1
High Temperature/ Humidity storage	The module should be allowed to stand at 60 $^{\circ}$ C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C ,90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation $-20^{\circ}C$ $25^{\circ}C$ $70^{\circ}C$ 30min 5min 30min 1 cycle	-20°C/70°C 10 cycles	
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude : 1.5mm Vibration Frequency : 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=±600V(contact), ±800v(air), RS=330Ω CS=150pF 10 times	

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal

Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

## **11.Backlight Information**

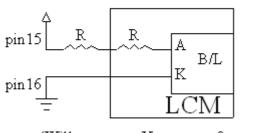
Specification

PARAMETER	SYMBOL	MIN	ТҮР	MAX	UNIT	TEST CONDITION
Supply Current	ILED	25	80	100	mA	V=3.5V(Note 1)
Supply Voltage	V	3.4	3.5	3.6	V	-
Reverse Voltage	VR	_	_	5	V	-
Luminance (Without LCD)	IV	480	600	_	CD/M <sup>2</sup>	ILED=80mA
LED Life Time (For Reference only)	_	_	50K	_	Hr.	ILED=80mA 25℃,50-60%RH, (Note 2)
Color	Yellow-gree	en	1	1		

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

Note 1: Supply current minimum value is only for reference since LED brightness efficiency keeps enhancing. Current consumption becomes less and less to achieve the same luminance.

Note 1:50K hours is only an estimate for reference.



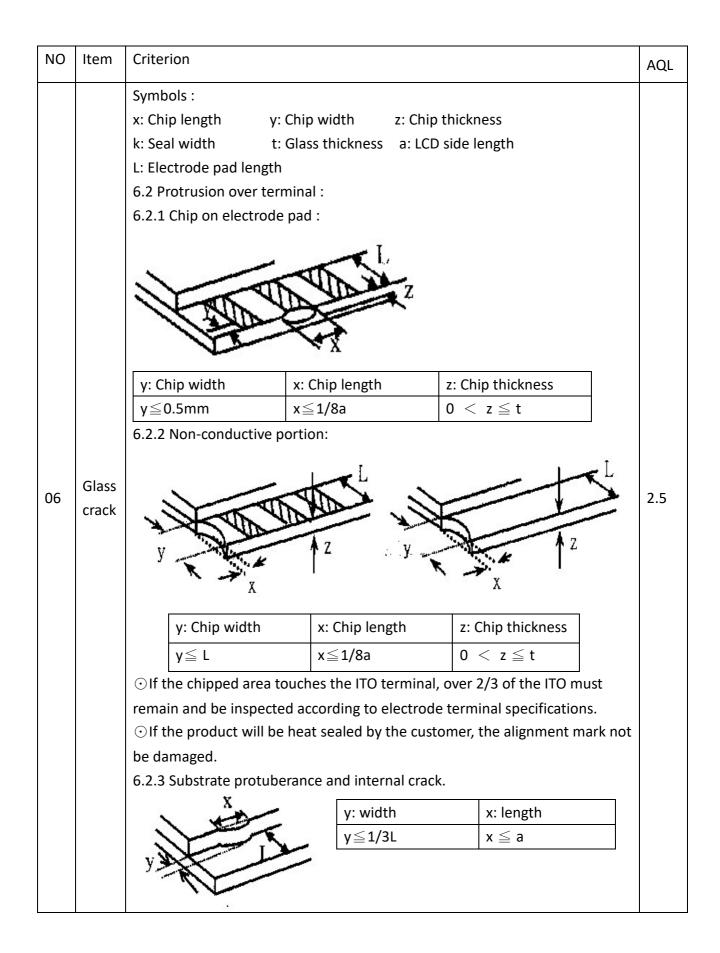
2.Drive from pin15,pin16

(Will never get Vee output from pin15)

## **12.Inspection specification**

NO	Item	Criterion				AQL
01	Electrical Testing	Cinterior         Missing vertical, horizontal segment, segment contrast defect.         Missing character, dot or icon.         Display malfunction.         No function or no display.         Current consumption exceeds product specifications.         LCD viewing angle defect.         Mixed product types.         Contrast defect.         2.1 White and black spots on display ≤ 0.25mm, no more than				
02	Black or white spots on LCD (display only)	<ul><li>three white or black spots present.</li><li>2.2 Densely spaced: No more than two spots or lines within</li><li>3mm</li></ul>				
	LCD black spots, white spots,	3.1 Round type $\Phi = (x + y) / 2$	: As follov	ving_drawing $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi$	Acceptable Q TY Accept no dense 2 1 0	2.5
03	contaminatio n (non- display)	3.2 Line type : (	As followi	w drawing)         Width         W $\leq$ 0.02         0.02 < W $\leq$ 0.03         0.03 < W $\leq$ 0.05         0.05 < W	Acceptable Q TY Accept no dense 2 As round type	2.5
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction.		Size $\Phi$ $\Phi \leq 0.20$ $0.20 < \Phi \leq 0.50$ $0.50 < \Phi \leq 1.00$ $1.00 < \Phi$ Total Q TY	Acceptable Q TY Accept no dense 3 2 0 3 3	2.5

NO	ltem	Criterion				
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination				
		Symbols Define: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length: 6.1 General glass chip : 6.1.1 Chip on panel surface and crack between panels:				
06	Chipped glass	z: Chip thickness $Z \le 1/2t$ $1/2t < z \le 2t$	y: Chip width Not over viewing area Not exceed 1/3k	x: Chip length $x \le 1/8a$ $x \le 1/8a$	2.5	
		6.1.2 Corner crack:	ore chips, x is total leng			
		z: Chip thickness $Z \leq 1/2t$	y: Chip width Not over viewing area	x: Chip length x≦1/8a		
		1/2t <z≦2t< td=""><td>Not exceed 1/3k</td><td>x≦1/8a</td><td></td></z≦2t<>	Not exceed 1/3k	x≦1/8a		
		$\odot$ If there are 2 or m	ore chips, x is the total l	ength of each chip.		



NO	Item	Criterion	AQL		
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5		
		8.1 Illumination source flickers when lit.	0.65		
	Backlight	8.2 Spots or scratched that appear when lit must be judged.	2.5		
08	elements	Using LCD spot, lines and contamination standards.			
		8.3 Backlight doesn't light or color wrong.	0.65		
		9.1 Bezel may not have rust, be deformed or have fingerprints,	2.5		
09	Bezel	stains or other contamination.			
		9.2 Bezel must comply with job specifications.	0.65		
		10.1 COB seal may not have pinholes larger than 0.2mm or	2.5		
		contamination.			
		10.2 COB seal surface may not have pinholes through to the IC.	2.5		
		10.3 The height of the COB should not exceed the height	0.65		
	РСВ 、 СОВ	indicated in the assembly diagram.			
		10.4 There may not be more than 2mm of sealant outside the	2.5		
		seal area on the PCB. And there should be no more than three			
		places.			
		10.5 No oxidation or contamination PCB terminals.	2.5		
10		10.6 Parts on PCB must be the same as on the production	0.65		
10		characteristic chart. There should be no wrong parts, missing			
		parts or excess parts.			
		10.7 The jumper on the PCB should conform to the product	0.65		
		characteristic chart.			
		10.8 If solder gets on bezel tab pads, LED pad, zebra pad or	2.5		
		screw hold pad, make sure it is smoothed down.			
		10.9 The Scraping testing standard for Copper Coating of PCB	2.5		
		X			
		$\mathbf{Y}$ X * Y<=2mm <sup>2</sup>			
		11.1 No un-melted solder paste may be present on the PCB.	2.5		
	Soldering	11.2 No cold solder joints, missing solder connections,	2.5		
11		oxidation or icicle.			
		11.3 No residue or solder balls on PCB.	2.5		
		11.4 No short circuits in components on PCB.	0.65		

NO	Item	Criterion	AQL
		12.1 No oxidation, contamination, curves or, bends on interface	2.5
		Pin (OLB) of TCP.	
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on product.	2.5
	General appearance	12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface	2.5
		pin must be present or look as if it cause the interface pin to	
		sever.	2.5
		12.6 The residual rosin or tin oil of soldering (component or chip	
12		component) is not burned into brown or black color.	2.5
		12.7 Sealant on top of the ITO circuit has not hardened.	0.65
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 LCD pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on packaging	
		specification sheet.	0.65
		12.11 Product dimension and structure must conform to product	
		specification sheet.	0.65
		12.12 Visual defect outside of VA is not considered to be	
		rejection.	

# <u>13.Material List of Components for</u> <u>RoHs</u>

1. Producer hereby declares that all of or part of products including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS.						

2.Process for RoHS requirement : (only for RoHS inspection)

- (1) Use the Sn/Ag/Cu soldering surface ; the surface of Pb-free solder is rougher than we used before.
- (2) Heat-resistance temp. :

Reflow : 250°C,30 seconds Max. ;

Connector soldering wave or hand soldering : 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235 $\pm$ 5°C ;

Recommended customer's soldering temp. of connector : 280°C, 3 seconds.

## **14.Recommendable Storage**

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.